

AMENDMENTS TO THE CLAIMS

Please amend the claims as indicated in the following listing of all claims:

1. (Canceled)
2. (Currently amended) The apparatus, as recited in claim [[1]]23, wherein the aperture is substantially parallel to a plane of current flow in the inductor.
3. (Canceled)
4. (Currently amended) The apparatus, as recited in claim [[1]]23, wherein the electrically conductive links reduce an effect of electromagnetic signals external to the electrically conductive enclosure on the inductor.
5. (Currently amended) The apparatus, as recited in claim [[1]]23, wherein the electrically conductive links reduce coupling in the inductor from external sources by approximately 6dB.
6. (Currently amended) The apparatus, as recited in claim [[1]]23, wherein the electrically conductive links are approximately 5 μ m wide.
7. (Currently amended) The apparatus, as recited in claim [[1]]23, wherein the electrically conductive links are formed in the one or more traditional integrated circuit layers.
8. (Currently amended) The apparatus, as recited in claim [[1]]23, wherein the electrically conductive enclosure includes a top plate, a bottom plate, and sidewalls.
9. (Canceled)
10. (Original) The apparatus, as recited in claim 8, wherein the aperture is formed in the bottom plate.

11. (Original) The apparatus, as recited in claim 8, wherein the bottom plate is formed in one or more integrated circuit metal layers.

12. (Original) The apparatus, as recited in claim 8, wherein the top plate is formed in a metal layer.

13. (Original) The apparatus, as recited in claim 8, wherein the top plate is formed in a redistribution layer.

14. (Original) The apparatus, as recited in claim 8, wherein the top plate is formed in a package substrate.

15. (Currently amended) The apparatus, as recited in claim [[1]]23, wherein the inductor is formed at least partially in one or more metal layers of an integrated circuit die thicker than others of the metal layers.

16. (Currently amended) The apparatus, as recited in claim [[1]]23, wherein the inductor is formed at least partially in one or more redistribution layers formed on an integrated circuit die.

17. (Currently amended) The apparatus, as recited in claim [[1]]23, wherein the inductor is formed on an integrated circuit die.

18. (Original) The apparatus, as recited in claim 17, wherein a conductor forming the inductor is 10 μ m wide.

19. (Original) The apparatus, as recited in claim 17, wherein the aperture and the inductor are effectively spaced at least 10.25 μ m apart.

20. (Canceled)

21. (Canceled)

22. (Canceled)

23. (Currently amended) An apparatus comprising:
an inductor;
an electrically conductive enclosure electromagnetically shielding the inductor, the
electrically conductive enclosure having an aperture at least as large as the
inductor, the aperture being substantially centered around a projected surface of
~~the circuit element~~ inductor; and
one or more electrically conductive links extending across the aperture and electrically
coupled to the electrically conductive enclosure,
wherein individual ones of the electrically conductive links are coupled to each other by
an electrically conductive link perpendicular to the individual ones of the
electrically conductive links.

24-45. (Canceled)

46. (Previously Presented) The apparatus, as recited in claim 23, wherein the aperture is
formed in an electrically conductive plate of the electrically conductive enclosure.

47. (Previously Presented) The apparatus, as recited in claim 46, wherein the electrically
conductive plate is formed by a plurality of continuous conductive patterns, each of the
continuous conductive patterns being substantially concentric with respect to the aperture.

48. (Canceled)

49. (Canceled)

50. (Canceled)

51. (Previously Presented) The apparatus, as recited in claim 23, wherein the aperture is
at least as large as the inductor and is substantially centered around a projected surface of the
inductor.

52. (Canceled)

53. (Previously Presented) The apparatus, as recited in claim 55, wherein the aperture is formed in an electrically conductive plate of the electrically conductive enclosure.

54. (Previously Presented) The apparatus, as recited in claim 53, wherein the electrically conductive plate is formed by a plurality of continuous conductive patterns, each of the continuous conductive patterns being substantially concentric with respect to the aperture.

55. (Currently amended) An apparatus comprising:

an inductor;

~~an electrically conductive enclosure electromagnetically shielding the inductor, the electrically conductive enclosure having an aperture at least as large as the inductor, the aperture being substantially centered around a projected surface of the inductor; and~~

~~one or more electrically conductive links extending across the aperture and electrically coupled to the electrically conductive enclosure,~~

The apparatus, as recited in claim 23, wherein the aperture has an approximate diameter determined by adding an approximate outer diameter of the inductor to an approximate inner diameter of the inductor.